## TVS4201MR6

## Transient Voltage Suppressors

## Low Clamping Voltage Surge Protection Diode Array

The TVS4201MR6 transient voltage suppressor is designed to protect high speed data lines from ESD, EFT, and lightning surges.

## Features

- Protection for the Following IEC Standards:

IEC 61000-4-2 (ESD) $\pm 30 \mathrm{kV}$ (Contact)
IEC 61000-4-5 (Lightning) 25 A ( $8 / 20 \mu \mathrm{~s}$ )

- Low Clamping Voltage
- Low Leakage
- UL Flammability Rating of $94 \mathrm{~V}-0$
- SZ Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are $\mathrm{Pb}-$ Free, Halogen Free/BFR Free and are RoHS Compliant


## Typical Applications

- High Speed Communication Line Protection
- USB 1.1 and 2.0 Power and Data Line Protection
- Digital Video Interface (DVI)
- Monitors and Flat Panel Displays

MAXIMUM RATINGS $\left(T_{J}=25^{\circ} \mathrm{C}\right.$ unless otherwise noted)

| Rating | Symbol | Value | Unit |
| :--- | :---: | :---: | :---: |
| Peak Power Dissipation <br> $8 / 20 ~ \mu \mathrm{~s} @$ <br> $\mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}($ Note 1) | $\mathrm{P}_{\mathrm{pk}}$ | 500 | W |
| Operating Junction Temperature Range | $\mathrm{T}_{\mathrm{J}}$ | -40 to +125 | ${ }^{\circ} \mathrm{C}$ |
| Storage Temperature Range | $\mathrm{T}_{\text {stg }}$ | -55 to +150 | ${ }^{\circ} \mathrm{C}$ |
| Lead Solder Temperature - <br> Maximum (10 Seconds) | $\mathrm{T}_{\mathrm{L}}$ | 260 | ${ }^{\circ} \mathrm{C}$ |
| IEC 61000-4-2 Air (ESD) <br> IEC 61000-4-2 Contact (ESD) | ESD | $\pm 30$ | kV |
| IEC 61000-4-4 (5/50 ns) | EFT | 40 | A |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected

1. Non-repetitive current pulse per Figure 1 (Pin 5 to Pin 2)

See Application Note AND8308/D for further description of survivability specs.

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PIN CONFIGURATION AND SCHEMATIC


ORDERING INFORMATION

| Device | Package | Shipping |
| :---: | :---: | :---: |
| TVS4201MR6T1G | TSOP-6 <br> (Pb-Free) |  <br> Reel |
| SZTVS4201MR6T1G | TSOP-6 <br> (Pb-Free) |  <br> Reel |

$\dagger$ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

## TVS4201MR6

## ELECTRICAL CHARACTERISTICS

( $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ unless otherwise noted)

| Symbol | Parameter |
| :---: | :--- |
| $\mathrm{I}_{\mathrm{PP}}$ | Maximum Reverse Peak Pulse Current |
| $\mathrm{V}_{\mathrm{C}}$ | Clamping Voltage @ $\mathrm{I}_{\mathrm{PP}}$ |
| $\mathrm{V}_{\mathrm{RWM}}$ | Working Peak Reverse Voltage |
| $\mathrm{I}_{\mathrm{R}}$ | Maximum Reverse Leakage Current @ $\mathrm{V}_{\mathrm{RWM}}$ |
| $\mathrm{V}_{\mathrm{BR}}$ | Breakdown Voltage $@ \mathrm{I}_{\mathrm{T}}$ |
| $\mathrm{I}_{\mathrm{T}}$ | Test Current |
| $\mathrm{I}_{\mathrm{F}}$ | Forward Current |
| $\mathrm{V}_{\mathrm{F}}$ | Forward Voltage @ $\mathrm{I}_{\mathrm{F}}$ |
| $\mathrm{P}_{\mathrm{pk}}$ | Peak Power Dissipation |
| C | Capacitance @ $\mathrm{V}_{\mathrm{R}}=0$ and $\mathrm{f}=1.0 \mathrm{MHz}$ |


*See Application Note AND8308/D for detailed explanations of datasheet parameters.

ELECTRICAL CHARACTERISTICS $\left(T_{J}=25^{\circ} \mathrm{C}\right.$ unless otherwise specified)

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Reverse Working Voltage | $\mathrm{V}_{\text {RWM }}$ | (Note 2) |  |  | 5.0 | V |
| Breakdown Voltage | $V_{B R}$ | $\mathrm{I}_{\mathrm{T}}=1 \mathrm{~mA}$, (Note 3) | 6.0 |  |  | V |
| Reverse Leakage Current | $\mathrm{I}_{\mathrm{R}}$ | $\mathrm{V}_{\mathrm{RWM}}=5 \mathrm{~V}$ |  |  | 1.0 | $\mu \mathrm{A}$ |
| Clamping Voltage ( $\mathrm{t}_{\mathrm{p}}=8 / 20 \mu \mathrm{~s}$ per Figure 1 ) | $\mathrm{V}_{\mathrm{C}}$ | IPP $=1 \mathrm{~A}$, Any I/O to GND |  |  | 8.5 | V |
|  |  | $\mathrm{I} P \mathrm{FP}=5 \mathrm{~A}$, Any I/O to GND |  |  | 9.0 |  |
|  |  | IPp $=8$ A, Any I/O to GND |  |  | 10 |  |
|  |  | IPp $=25 \mathrm{~A}$, Any I/O to GND |  |  | 12 |  |
| Junction Capacitance | $\mathrm{C}_{J}$ | $\mathrm{V}_{\mathrm{R}}=0 \mathrm{~V}, \mathrm{f}=1 \mathrm{MHz}$ between I/O Pins and GND |  | 3.0 | 5.0 | pF |
| Junction Capacitance | CJ | $\mathrm{V}_{\mathrm{R}}=0 \mathrm{~V}, \mathrm{f}=1 \mathrm{MHz}$ between I/O Pins |  | 1.5 | 3.0 | pF |

2. TVS devices are normally selected according to the working peak reverse voltage ( $\mathrm{V}_{\mathrm{RWM}}$ ), which should be equal or greater than the DC or continuous peak operating voltage level.
3. $\mathrm{V}_{\mathrm{BR}}$ is measured at pulse test current $\mathrm{I}_{\mathrm{T}}$.


Figure 1. IEC61000-4-5 8/20 $\mu$ s Pulse Waveform


Figure 2. Clamping Voltage vs. Peak Pulse Current ( $\mathrm{t}_{\mathrm{p}}=8 / 20 \mu \mathrm{~s}$ per Figure 1)


Figure 3. IEC61000-4-2 +8 kV Contact Clamping Voltage
IEC 61000-4-2 Spec.

| Level | Test Volt- <br> age (kV) | First Peak <br> Current <br> $(A)$ | Current at <br> $\mathbf{3 0}$ ns (A) | Current at <br> $\mathbf{6 0} \mathbf{n s}(\mathbf{A})$ |
| :---: | :---: | :---: | :---: | :---: |
| 1 | 2 | 7.5 | 4 | 2 |
| 2 | 4 | 15 | 8 | 4 |
| 3 | 6 | 22.5 | 12 | 6 |
| 4 | 8 | 30 | 16 | 8 |



Figure 4. IEC61000-4-2 -8 kV Contact Clamping Voltage


Figure 5. IEC61000-4-2 Spec


Figure 6. Diagram of ESD Test Setup

The following is taken from Application Note AND8308/D - Interpretation of Datasheet Parameters for ESD Devices.

## ESD Voltage Clamping

For sensitive circuit elements it is important to limit the voltage that an IC will be exposed to during an ESD event to as low a voltage as possible. The ESD clamping voltage is the voltage drop across the ESD protection diode during an ESD event per the IEC61000-4-2 waveform. Since the IEC61000-4-2 was written as a pass/fail spec for larger
systems such as cell phones or laptop computers it is not clearly defined in the spec how to specify a clamping voltage at the device level. ON Semiconductor has developed a way to examine the entire voltage waveform across the ESD protection diode over the time domain of an ESD pulse in the form of an oscilloscope screenshot, which can be found on the datasheets for all ESD protection diodes. For more information on how ON Semiconductor creates these screenshots and how to interpret them please refer to AND8307/D.

TYPICAL PERFORMANCE CURVES
( $\mathrm{T}_{\mathrm{J}}=25^{\circ} \mathrm{C}$ unless otherwise noted)


Figure 7. Pulse Derating Curve


Figure 8. Junction Capacitance vs Reverse Voltage


Figure 9. RF Insertion Loss

TYPICAL APPLICATIONS


Figure 10. Protection for Ethernet 10/100 (Differential mode)


Figure 11. TI/E1 Interface Protection

## PACKAGE DIMENSIONS

TSOP-6
CASE 318G-02
ISSUE V


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSIONS D AND E1 ARE DETERMINED AT DATUM H.
5. PIN ONE INDICATOR MUST BE LOCATED IN THE INDICATED ZONE.

| DIM | MILLIMETERS |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: |
|  | MIN | NOM | MAX |  |  |
| A | 0.90 | 1.00 | 1.10 |  |  |
| A1 | 0.01 | 0.06 | 0.10 |  |  |
| b | 0.25 | 0.38 | 0.50 |  |  |
| c | 0.10 | 0.18 | 0.26 |  |  |
| D | 2.90 | 3.00 | 3.10 |  |  |
| E | 2.50 | 2.75 | 3.00 |  |  |
| E1 | 1.30 | 1.50 | 1.70 |  |  |
| $\mathbf{e}$ | 0.85 | 0.95 | 1.05 |  |  |
| L | 0.20 | 0.40 | 0.60 |  |  |
| L2 | 0.25 BSC |  |  |  |  |
| M | $0^{\circ}$ | - |  |  | $10^{\circ}$ |

## RECOMMENDED

 SOLDERING FOOTPRINT*
*For additional information on our $\mathrm{Pb}-F r e e$ strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.


#### Abstract

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